

In the Specification:

Please amend paragraphs [0018] and [0019] as follows:

[0018] Figure 2 shows the wafer according to Figure 1 which has been provided with a casting compound which encloses the 3D element; [[and]]

[0019] Figure 3 shows the coated wafer after exposing the contact area of the 3D element[.].];

Please add the following paragraphs after paragraph [0019] as follows:

[0019A] Figure 4 shows the wafer being attached to a printed circuit board or lead frame; and

[0019B] Figure 5 shows a wafer with separation corridors.

Please add the following paragraph between paragraphs [0027] and [0028] as follows:

[0027A] After applying a casting compound 5, the connection area 3 can be electrically coupled to a terminal 7 of a second apparatus 8, as shown in Figure 4. The second apparatus 8 can be a printed circuit board or a lead frame. The connection area 3 can be electrically coupled by soldering the connection area 3 to the terminal 7 with a solder material 9.

Please amend paragraphs [0028] and [0029] as follows:

[0028] Since the individual separation of the chips from the wafer assembly is made more difficult by the coating with the casting compound 5, it is expedient that the separation corridors 6 (e.g., scribe lines) between the chips are exposed before the separation of the latter from the wafer 1. This procedure, which is illustrated in Figure 5, may take place by means of customary photolithographic methods, or else by working with a laser beam.

[0029] If the wafers 1 are separated by working with a laser, it is possible to dispense with the prior exposure of the separation corridors 6.